



**PATENT APPLICATION**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Masatake NAKANO et al.

Group Art Unit: 1763

Application No.: 09/857,569

Examiner: G. Goudreau

Filed: June 7, 2001

Docket No.: 109716

For: METHOD FOR PRODUCING BONDING WAFER AND BONDING WAFER

**AMENDMENT UNDER 37 C.F.R. §1.111**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In reply to the August 19, 2003 Office Action, please consider the following:

**Amendments to the Claims** as reflected in the listing of claims; and

**Remarks.**